

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1081	(228/180.1).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/13 07:31
L2	539083	(((circuit PC wiring mount\$4) adj (board card module)) pcb PWB motherboard mother adj board)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:37
L3	8048588	(adjacent abut\$4 juxtapos\$3 proxim\$5 side adjoin\$4 lateral\$4 neighboring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:38
L4	1623286	pattern	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:38
L5	3561394	revers\$3 opposite mirror\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:39
L6	46183	4 near6 5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:39
L7	37970	2 near2 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 07:40
L8	207	6 with 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:04
L9	4154298	arra\$4 matrix	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:04
L10	9031	9 near 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:10

L11	901	6 near9 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:05
L12	66	10 and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:41
L13	263	6 same 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:41
L14	56	13 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:42
L15	1007	6 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:42
L16	800	15 not 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:42
L17	65	16 and 10	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 08:45
L18	1	("6664864").URPN.	USPAT	OR	ON	2005/09/13 08:58
L19	8	("4750246" "5405476" "5446954" "6229249" "6229404" "6239669" "6304151" "6456168").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/13 08:58
L20	4233	9 adj 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:11
L21	2223094	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:12

L22	1901	bill adj2 material	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:12
L23	5	20 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:15
L24	8	10 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:16
L25	3	24 not 23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:17
L26	8	6 same 20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:17
L27	68	6 and 20	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 09:18